**25E. Processing of New Materials for Future Technologies**

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| Session Chair:| Dr. Yi-Chiau Huang (Applied Materials)  
Dr. Yoshiki Yamamoto (Renesas) |

**[25E-1] [Invited] 17:00-17:25**

**Contacts for 2D-Material MOSFETs: Recent Advances and Outstanding Challenges**

Steven J. Koester  
*University of Minnesota-Twin Cities*

**[25E-2] 17:25-17:45**

**Grain-Size Enlargement of MoS$_2$ Film by Low-Rate Sputtering with Molybdenum Grid**

Shinya Imai, Ryo Ono, Iriya Muneta, Kuniyuki Kakushima, Tetsuya Tatsumi, Shigetaka Tomiya, Kazuo Tsutsui and Hitoshi Wakabayashi  
*Tokyo Institute of Technology*

**[25E-3] 17:45-18:05**

**Development of MFMIS Gatestack with Thick Hafnium Zirconium Oxide (HZO) for Nonvolatile Memory Application**

Bohyeon Kang$^1$, Jongseo Park$^1$, Junghyeon Wang$^2$, Sangho Lee$^2$, Hunbeom Shin$^2$, Je hyun An$^1$, Hyunseo You$^1$, Sung-Min Ahn$^1$, Sanghun Jeon$^2$ and Rock-Hyun Baek$^1$  
$^1$Pohang University of Science and Technology, $^2$Korea Advanced Institute of Science and Technology


**Alternative EUV Mask Absorber with Platinum-Based Alloy for High-NA EUV Lithography**

Yunsoo Kim$^{1,2}$, Dongmin Jeong$^{1,2}$, Minsun Cho$^{1,2}$ and Jinho Ahn$^{1,2}$  
$^1$Hanyang University, $^2$EUV Industry-University Collaboration Center